

www.ti.com

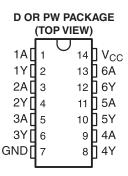
SCAS783D - OCTOBER 2004-REVISED JULY 2012

## **HEX BUFFER/DRIVER** WITH OPEN-DRAIN OUTPUTS

Check for Samples: SN74LVC07A-Q1

#### **FEATURES**

- **Qualified for Automotive Applications**
- Operates From 1.65 V to 5 V
- Inputs and Open-Drain Outputs Accept Voltages up to 5.5 V
- Latch-Up Performance Exceeds 250 mA Per JESD 17



#### **DESCRIPTION/ORDERING INFORMATION**

This hex buffer/driver is designed for 1.65-V to 5.5-V V<sub>CC</sub> operation.

The outputs of the SN74LVC07A device are open drain and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 24 mA.

Inputs can be driven from 1.8-V, 2.5-V, 3.3-V (LVTTL), or 5-V (CMOS) devices. This feature allows the use of this device as a translator in a mixed-system environment.

#### ORDERING INFORMATION(1)

T <sub>A</sub>	PACK	AGE <sup>(2)</sup>	ORDERABLE PART NUMBER	TOP-SIDE MARKING		
–40°C to 125°C	SOIC - D	Reel of 2500	SN74LVC07AQDRQ1	LVC07AQ		
	TSSOP – PW	Reel of 2000	SN74LVC07AQPWRQ1	LVC07AQ		

For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

#### **Table 1. FUNCTION TABLE** (EACH BUFFER/DRIVER)

-	
INPUT A	OUTPUT Y
Н	Н
L	L

#### LOGIC DIAGRAM, EACH BUFFER/DRIVER (POSITIVE LOGIC)





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



## Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	6.5	V
$V_{I}$	Input voltage range <sup>(2)</sup>	-0.5	6.5	V	
Vo	Output voltage range		-0.5	6.5	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA
$I_{OK}$	Output clamp current	V <sub>O</sub> < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through V <sub>CC</sub> or GND			±100	mA
0	Daglage thermal impedance (3)	D package		86	°C // //
$\theta_{JA}$	Package thermal impedance (3)	PW package		113	°C/W
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## Recommended Operating Conditions<sup>(1)</sup>

			MIN	MAX	UNIT	
$V_{CC}$	Supply voltage		1.65	5.5	V	
		V <sub>CC</sub> = 1.65 V to 1.95 V	0.65 × V <sub>CC</sub>			
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
		V <sub>CC</sub> = 2.7 V to 3.6 V	2			
	V <sub>CC</sub> = 1.65 V to 1.95 V		(	0.35 × V <sub>CC</sub>		
$V_{IL}$	Low-level input voltage	V <sub>CC</sub> = 2.3 V to 2.7 V		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		
VI	Input voltage		0	5.5	V	
Vo	Output voltage		0	5.5	V	
		V <sub>CC</sub> = 1.65 V		4		
	Low lovel output outront	V <sub>CC</sub> = 2.3 V		12	A	
I <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA	
		V <sub>CC</sub> = 3 V		24		
T <sub>A</sub>	Operating free-air temperature		-40	125	°C	

<sup>(1)</sup> All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. See the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>(3)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

www.ti.com

#### **Electrical Characteristics**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN TYP <sup>(1)</sup> MAX	UNIT
	$I_{OL} = 100 \ \mu A$	1.65 V to 3.6 V	0.2	
$V_{OL}$	$I_{OL} = 4 \text{ mA}$	1.65 V	0.45	
	1 12 m/s	2.3 V	0.7	V
	I <sub>OL</sub> = 12 mA	2.7 V	0.4	
	$I_{OL} = 24 \text{ mA}$	3 V	0.65	
I <sub>I</sub>	$V_I = 5.5 \text{ V or GND}$	3.6 V	±5	μΑ
I <sub>CC</sub>	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V	10	μΑ
ΔI <sub>CC</sub>	One input at V <sub>CC</sub> – 0.6 V, Other inputs at V <sub>CC</sub> or GND	2.7 V to 3.6 V	500	μΑ
C <sub>i</sub>	$V_I = V_{CC}$ or GND	3.3 V	5	pF

<sup>(1)</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

## **Switching Characteristics**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	Α	Y	1	3.5	1	2.8		3	1	2.9	ns

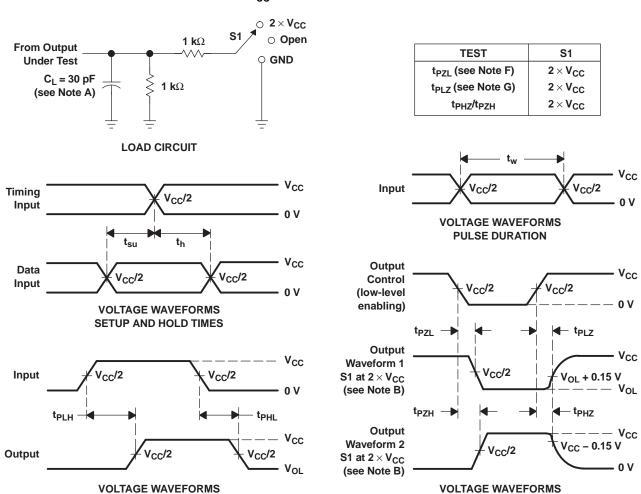
## **Operating Characteristics**

 $T_A = 25$ °C

	PARAMETER	TEST	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT
	FARAWETER	CONDITIONS	TYP	TYP	TYP	ONII
$C_{pd}$	Power dissipation capacitance per buffer/driver	f = 10 MHz	1.8	2	2.5	рF



# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

PROPAGATION DELAY TIMES

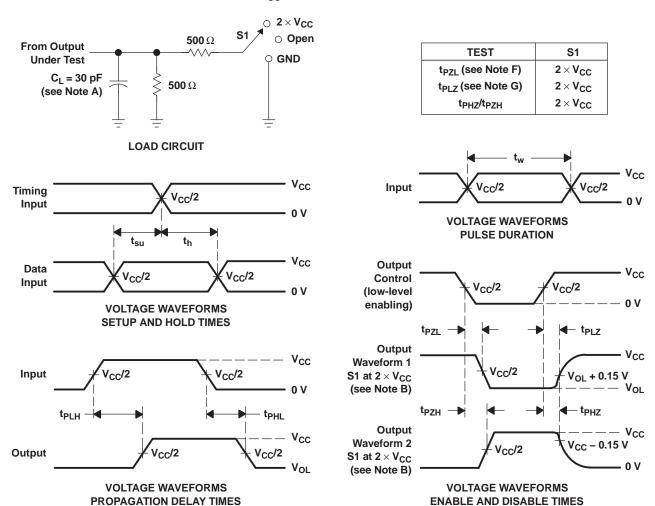
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_f \leq$  2 ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. Since this device has open-drain outputs, t<sub>PLZ</sub> and t<sub>PZL</sub> are the same as t<sub>pd</sub>.
- F. t<sub>PZI</sub> is measured at V<sub>CC</sub>/2.
- G.  $t_{PLZ}$  is measured at  $V_{OL}$  + 0.15 V.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**ENABLE AND DISABLE TIMES** 



# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

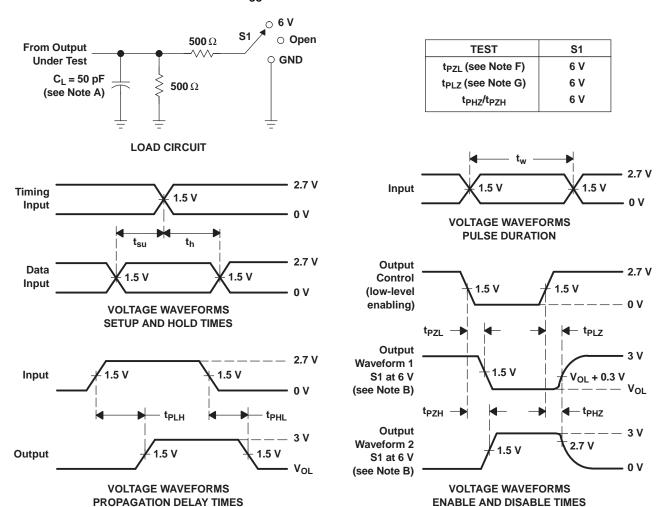


- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O}$  = 50  $\Omega$ ,  $t_{f} \leq$  2 ns.  $t_{f} \leq$  2 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E. Since this device has open-drain outputs, t<sub>PLZ</sub> and t<sub>PZL</sub> are the same as t<sub>pd</sub>.
  - F. t<sub>PZI</sub> is measured at V<sub>CC</sub>/2.
  - G.  $t_{PLZ}$  is measured at  $V_{OL}$  + 0.15 V.
  - H. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.7$ and 3.3 V $\pm$ 0.3 V



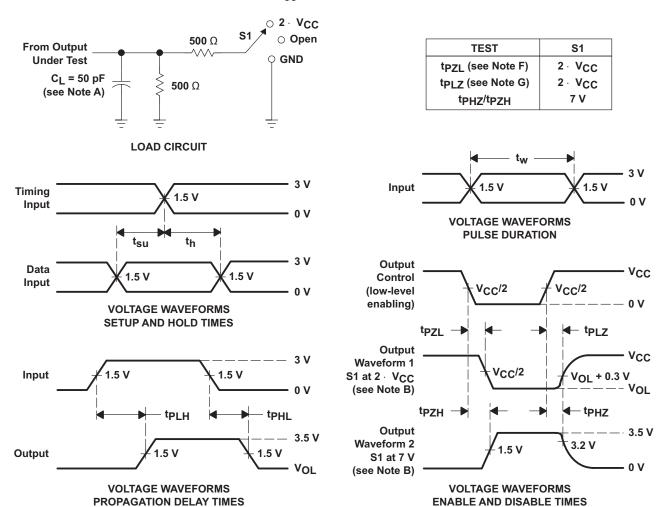
NOTES: A.  $C_L$  includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \ \Omega$ ,  $t_f \leq 2.5 \ ns$ ,  $t_f \leq 2.5 \ ns$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. Since this device has open-drain outputs, t<sub>PLZ</sub> and t<sub>PZL</sub> are the same as t<sub>pd</sub>.
- F. t<sub>PZI</sub> is measured at 1.5 V.
- G.  $t_{PLZ}$  is measured at  $V_{OL}$  + 0.3 V.
- H. All parameters and waveforms are not applicable to all devices.

Figure 3. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR $\leq$  10 MHz,  $Z_O$  = 50  $\Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E. Since this device has open-drain outputs,  $t_{PLZ}$  and  $t_{PZL}$  are the same as  $t_{pd}$ .
  - F. tpzl is measured at V<sub>CC</sub>/2.
  - G.  $t_{PLZ}$  is measured at  $V_{OL}$  + 0.3 V.
  - H. All parameters and waveforms are not applicable to all devices.

Figure 4. Load Circuit and Voltage Waveforms



## **REVISION HISTORY**

Cł	hanges from Revision C (December, 2007) to Revision D	Page
•	Changed from "Operates From 1.65 V to 3.6 V" to "Operates From 1.65 V to 5 V"	1
•	Changed from "This hex buffer/driver is designed for 1.65-V to 3.6-V $V_{CC}$ operation" to "This hex buffer/driver is designed for 1.65-V to 5.5-V $V_{CC}$ operation"	1
•	Changed supply voltage max value from 3.6 to 5.5	<mark>2</mark>
•	Added 4th PMI image	<mark>7</mark>



### PACKAGE OPTION ADDENDUM

10-Dec-2020

#### PACKAGING INFORMATION

www.ti.com

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LVC07AQPWRG4Q1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC07AQ	Samples
SN74LVC07AQPWRQ1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	LVC07AQ	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



## **PACKAGE OPTION ADDENDUM**

10-Dec-2020

#### OTHER QUALIFIED VERSIONS OF SN74LVC07A-Q1:

● Enhanced Product: SN74LVC07A-EP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Enhanced Product Supports Defense, Aerospace and Medical Applications

www.ti.com 9-Nov-2021

## TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

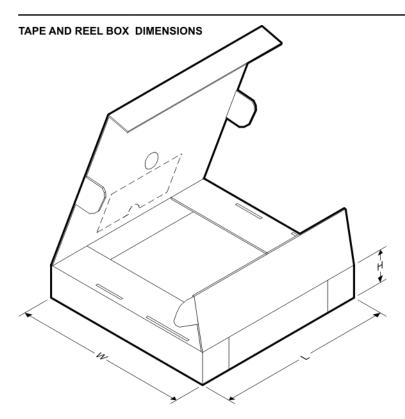
#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVC07AQPWRG4Q 1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74LVC07AQPWRQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

www.ti.com 9-Nov-2021



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVC07AQPWRG4Q1	TSSOP	PW	14	2000	853.0	449.0	35.0
SN74LVC07AQPWRQ1	TSSOP	PW	14	2000	853.0	449.0	35.0

PW (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



## PW (R-PDSO-G14)

## PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



#### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2021, Texas Instruments Incorporated